



FACED PANEL

CEPPO LS66

SUPPORT: Chipboard, MDF FORMAT: 5600 x 2070 mm THICKNESS: from 8 to 38 mm TEXTURE ORIENTATION: Vertical BACK TEXTURE: Ceppo

NOMINAL OVERTHICKNESS: +0.1 mm

LAMINATE

CEPPO LS66

TYPE: HPL FORMAT: 2760 x 2040 mm THICKNESS: 0.9 mm **EDGE**

CEPPO LS66

TYPE: ABS
HEIGHT: from 15 to 350 mm
THICKNESS: from 0.5 to 2.0 mm